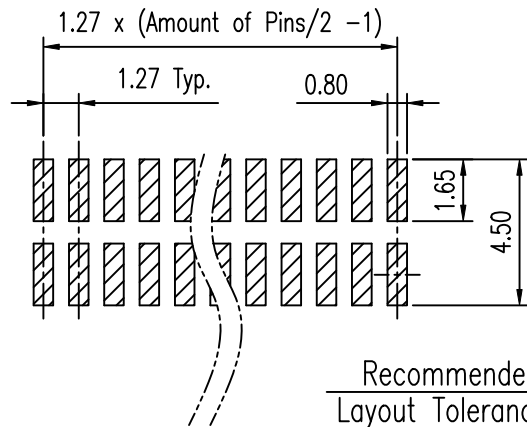
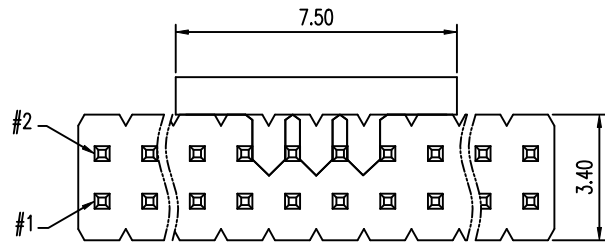
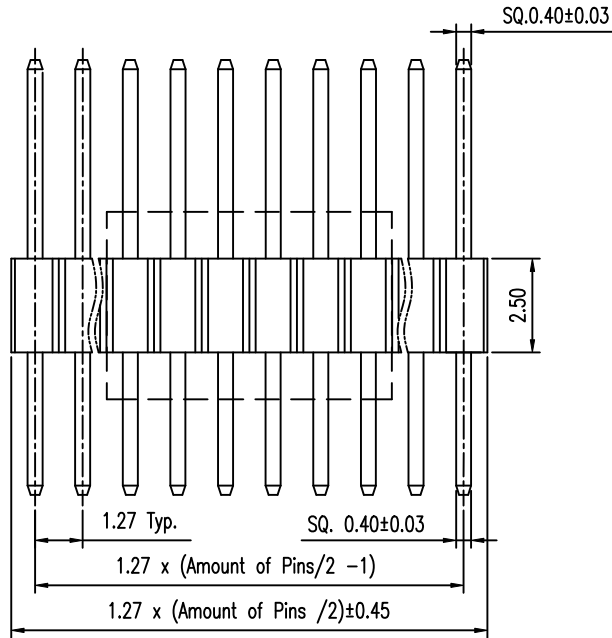
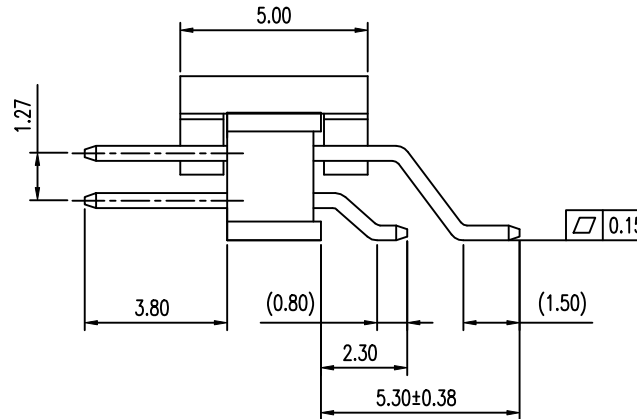




Recommended P.C.B. Layout
Layout Tolerance = ± 0.05 mm



NOTE:

- MATERIAL,
HOUSING: HIGH TEMP PLASTIC, UL94-V0, BLACK
TERMINAL: COPPER ALLOY, SQ=0.40±0.03MM
- FINISH:
TERMINAL: GOLD AT CONTACT,
G/F OVER 1um(40u")MIN Ni OVER ALL
- SPEC.:
PRODUCT SPEC: GS-12-629
PACKING SPEC: GS-14-1420
- THE HSG. WILL WITHSTAND EXPOSURE TO 260C
PEAK TEMP. FOR 10 SEC. IN A CONVECTION, INFRA-RED
OR VAPOR PHASE REFLOW OVEN.
- THE 0.15MM MIN. SOLDER PASTE IS RECOMMENDED
FOR REFLOW SOLDERING.

6. PRODUCT NUMBERING:

20021122 - 0 0 0 XX X X LF

LEAD FREE

PLATING:

- 1: GOLD FLASH ALL OVER
- 4: 0.25um(10u")GOLD AT CONTACT
- 8: 0.76um(30u")GOLD AT CONTACT

PACKING

D: TUBE+ CAP
T: TUBE

PIN COUNT

6,10,12,14,...., 98
(8 - 98 EVERY EVEN PIN)

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com	
ltr	ecn no	dr	date	linear	.X ± 0.38			
A	T09-1117	S.LIN	09/15/09	linear	.XX ± 0.25	projection	 title 1.27X1.27MM BTB,HEADER UNSTRODED, SMT	
B	T09-1155	S.LIN	12/03/09		.XXX ± 0.10			
C	T10-0014	S.LIN	01/28/10	angles	0° $\pm 2^\circ$		 product family 585 size dwg no	
D	T11-0029	S.LIN	11'-06-14	dr	STERLING LIN 09/15/09	MM		
				engr	STERLING LIN 09/15/09		 code TWN	
				chr	GARY HSIEH 09/15/09	scale		
				appd	JOSEPH HSIA 09/15/09	NA	 sheet 1 of 1	
sheet index	revision	D					 cage code	
	sheet	1						